

SURFACE PREPARATION FOR BONDING

Environmental conditions.

- Substrate temperature must be between 10 and 35°C and at least 3°C above the dew point.
- Relative Humidity must be less than 80%

Substrate Preparation.

- Surfaces to be bonded must be clean and activated by surface abrasion (abrasive blasting, grinding, wire brushes, sanding). This is followed by removal of loose debris and solvent washing.
- Greasy, oily substrates should be pre-washed to clean the surface. Hot water/detergent is a suitable alternative to solvent washing. Rinse with clean water.
- Equipment to be refurbished may require UHPW washing or steam cleaning to remove any engrained material such as salt and oils.
- Equipment where paint or other lining is removed by abrasive blasting must be washed down as above to ensure removal of any surface salt contamination.
- Wear resistant ceramic tiles are normally used as received. Wear gloves when handling to prevent surface contamination.
- FRP is prepared by removing the glossy gel coat usually by sanding or grinding, removing any loose debris and solvent wiping.
- Vulcanised rubber is buffed with a 24 or 36 grit pad at 3000 rpm to give a rough surface finish. Do not scorch/burn the surface. Remove debris and solvent wipe. A chlorination etch procedure may also be suitable depending on the rubber grade. Contact GARC for information.
- Concrete should be prepared by either acid etching or grinding to remove laitance and leave a profiled surface. Wet/damp concrete must be allowed to dry prior to adhesive application.